SDAS142C - JULY 1987 - REVISED AUGUST 1995

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- pnp Inputs Reduce dc Loading
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

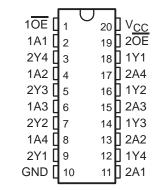
description

These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. With the 'ALS240A, 'ALS241C, 'AS240A, and 'AS241A, these devices provide the choice of selected combinations of inverting outputs, symmetrical active-low output-enable (OE) inputs, and complementary OE and OE inputs.

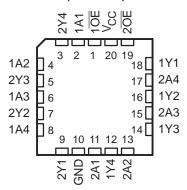
The -1 version of SN74ALS244C is identical to the standard version, except that the recommended maximum I_{OL} for the -1 version is 48 mA. There is no -1 version of the SN54ALS244C.

The SN54ALS244C and SN54AS244A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS244C and SN74AS244A are characterized for operation from 0°C to 70°C.

SN54ALS244C, SN54AS244A . . . J PACKAGE SN74ALS244C, SN74AS244A . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS244C, SN54AS244A . . . FK PACKAGE (TOP VIEW)



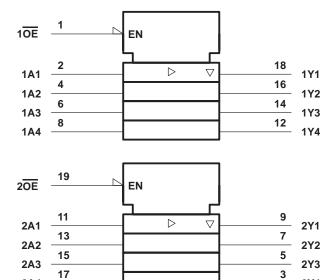
FUNCTION TABLE (each buffer)

INPU	JTS	OUTPUT
OE	Α	Y
L	Н	Н
L	L	L
Н	Χ	Z

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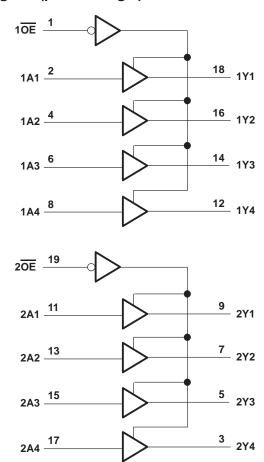
logic symbol[†]

2A4



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

2Y4

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54ALS244C	55°C to 125°C
SN74ALS244C	0°C to 70°C
Storage temperature range	−65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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recommended operating conditions

		SNS	54ALS24	4C	SN7	'4ALS24	4C	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
\/	Low level input veltage			0.8†			0.8	V
VIL	Low-level input voltage			0.7‡				V
lOH	High-level output current			-12			-15	mA
la.	Low-level output current			12			24	mA
IOL	Low-level output current						48§	IIIA
TA	Operating free-air temperature	-55		125	0		70	°C

[†] Applies over temperature range –55°C to 70°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST (CONDITIONS	SNS	4ALS24	4C	SN7	4ALS24	4C	UNIT
PARAMETER	lE31 C	CONDITIONS	MIN	TYP¶	MAX	MIN	TYP¶	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
	V _{CC} = 4.5 V to 5.5 V	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		VCC -2	2		
Vari	VCC = 4.5 V to 5.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						v
	vCC = 4.5 v	$I_{OH} = -15 \text{ mA}$				2			
		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
VOL	$V_{CC} = 4.5 \text{ V}$	I _{OL} = 24 mA					0.35	0.5	V
		I _{OL} = 48 mA (-1 version)					0.35	0.5	
lozh	$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			20			20	μΑ
lozL	$V_{CC} = 5.5 \text{ V},$	V _O = 0.4 V			-20			-20	μΑ
lj	$V_{CC} = 5.5 \text{ V},$	$V_I = 7 V$			0.1			0.1	mA
lіН	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
IO [#]	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
		Outputs high		9	18		9	17	
ICC	V _{CC} = 5.5 V	Outputs low		15	25		15	24	mA
		Outputs disabled		17	29		17	27	



[‡] Applies over temperature range 70°C to 125°C

[§] Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

[¶] All typical values are at V_{CC} = 5 V, T_A = 25°C.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R1 R2	= 50 pF = 500 £ 2 = 500 £	2,	,	UNIT
			SN54AL	S244C	SN74AL	S244C	
			MIN	MAX	MIN	MAX	
t _{PLH}	А	Y	1	16	2	10	ns
t _{PHL}	A	Y	3	12	3	10	115
^t PZH	ŌĒ	Y	1	26	3	20	ns
tPZL	OE	Y	1	24	3	20	115
^t PHZ	ŌĒ	V	2	10	2	10	ns
^t PLZ	OL .	'	1	26	1	13	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54AS244A	−55°C to 125°C
SN74AS244A	0°C to 70°C
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54AS244	1A	SN	74AS24	4A	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-12			-15	mA
loL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST O	ONDITIONS	SN	54AS24	4A	SN	74AS24	4A	LINUT
PARAMETER	IESI C	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2			
Va		$I_{OH} = -3 \text{ mA}$	2.4	3.4		2.4	3.4		V
VOH	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.4						V
		$I_{OH} = -15 \text{ mA}$				2.4			
Va	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55				V
VOL	VCC = 4.5 V	I _{OL} = 64 mA						0.55	V
lozh	$V_{CC} = 5.5 V,$	V _O = 2.7 V			50			50	μΑ
lozL	$V_{CC} = 5.5 V,$	V _O = 0.4 V			-50			-50	μΑ
Ц	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
lін	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
OE OE	V00 - 5 5 V	V _I = 0.4 V			-0.5			-0.5	mA
IIL A	V _{CC} = 5.5 V,	V = 0.4 V			-1			-1	ША
10 [‡]	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-50		-150	-50		-150	mA
		Outputs high		22	34		22	34	
ICC	V _{CC} = 5.5 V	Outputs low		60	90		60	90	mA
		Outputs disabled		34	54		34	54	

switching characteristics (see Figure 1)

PARAMETER	A Y 2 9 2 1 7 1 OF Y	§	UNIT				
						MAX	
^t PLH	Δ	.,	2	9	2	6.2	
^t PHL	А	Y	1	7	1	6.2	ns
^t PZH	<u></u>	V	1	10	1	9	ns
t _{PZL}	ÜE	Y	2	8	2	7.5	115
^t PHZ	ŌĒ	٧	1	6.5	1	6	ns
tPLZ	OL .	ľ	1	10.5	1	9	113

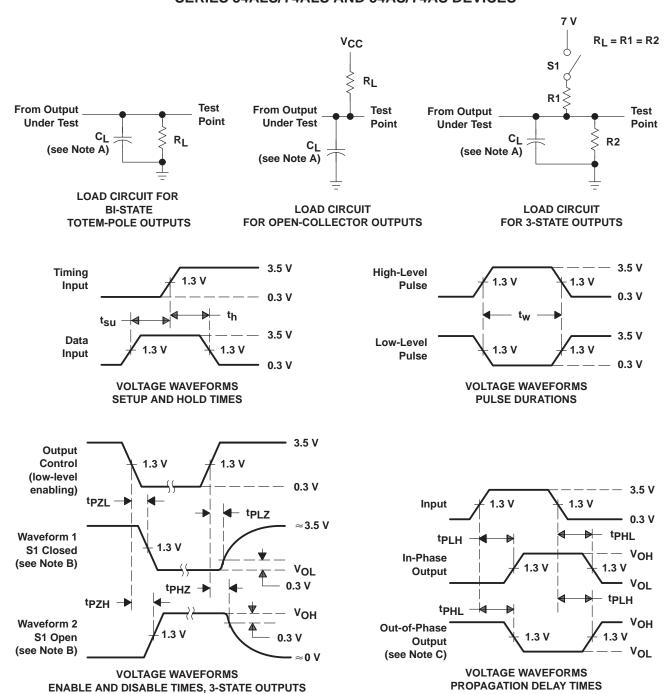
[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86839012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86839012A SNJ54ALS 244CFK	Samples
5962-8683901RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8683901RA SNJ54ALS244CJ	Samples
5962-8683901SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8683901SA SNJ54ALS244CW	Samples
5962-8683901VRA	ACTIVE	CDIP	J	20	20	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8683901VR A SNV54ALS244CJ	Samples
5962-8683901VSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8683901VS A SNV54ALS244CW	Samples
5962-9755901Q2A	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9755901Q2A SNJ54AS 244AFK	
5962-9755901QRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9755901QR A SNJ54AS244AJ	Samples
5962-9755901QSA	NRND	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9755901QS A SNJ54AS244AW	
JM38510/38303B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 38303B2A	Samples
JM38510/38303BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 38303BRA	Samples
M38510/38303B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 38303B2A	Samples
M38510/38303BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 38303BRA	Sample
SN54ALS244CJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS244CJ	Sample
SN54AS244AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS244AJ	Sample





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Orderable Device	Status	Package Type	_	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS244C-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C-1	Samples
SN74ALS244C-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C-1	Samples
SN74ALS244C-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS244C-1N	Samples
SN74ALS244C-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C-1	Samples
SN74ALS244C-1NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C-1	Samples
SN74ALS244CDBLE	OBSOLETI	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS244CDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G244C	Samples
SN74ALS244CDBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G244C	Samples
SN74ALS244CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C	Samples
SN74ALS244CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C	Samples
SN74ALS244CDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C	Samples
SN74ALS244CDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C	Samples
SN74ALS244CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS244CN	Samples
SN74ALS244CNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS244CN	Samples
SN74ALS244CNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C	Samples
SN74ALS244CNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS244C	Samples
SN74AS244ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS244A	Samples
SN74AS244ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS244A	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AS244AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS244AN	Samples
SN74AS244ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS244AN	Samples
SN74AS244ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS244A	Samples
SNJ54ALS244CFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86839012A SNJ54ALS 244CFK	Samples
SNJ54ALS244CJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8683901RA SNJ54ALS244CJ	Samples
SNJ54ALS244CW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8683901SA SNJ54ALS244CW	Samples
SNJ54AS244AFK	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9755901Q2A SNJ54AS 244AFK	
SNJ54AS244AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9755901QR A SNJ54AS244AJ	Samples
SNJ54AS244AW	NRND	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9755901QS A SNJ54AS244AW	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

PACKAGE OPTION ADDENDUM



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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS244C. SN54ALS244C-SP. SN54AS244A. SN74ALS244C. SN74AS244A:

Catalog: SN74ALS244C, SN54ALS244C, SN74AS244A

Military: SN54ALS244C, SN54AS244A

Space: SN54ALS244C-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS244C-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS244C-1NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74ALS244CDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS244CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS244CNSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74AS244ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AS244ANSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS244C-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS244C-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS244CDBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS244CDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS244CNSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS244ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AS244ANSR	SO	NS	20	2000	367.0	367.0	45.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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